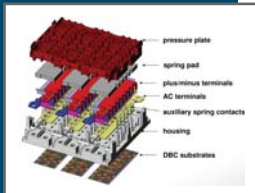
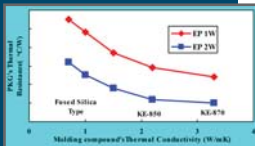
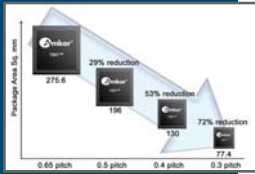


# Advanced Packaging Update: Market and Technology Trends

Vol. 1, 2008



Volume 1 of the Advanced Packaging Update for 2008 features an economic outlook with a discussion of the impact of higher energy prices. Also featured are package trends and roadmaps for products driving the growth in advanced packaging. Unit volume projections for advanced package growth are included. Package trends for notebook computers, mobile phones, and digital cameras are provided with details of the package types, I/O counts, minimum pitch, and package dimensions. Special sections are devoted to flash memory packaging trends and packaging for power devices. Also included are new developments in 3D packaging, including stacked die packaging, package-on-package (PoP), and through silicon via (TSV) technology.

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